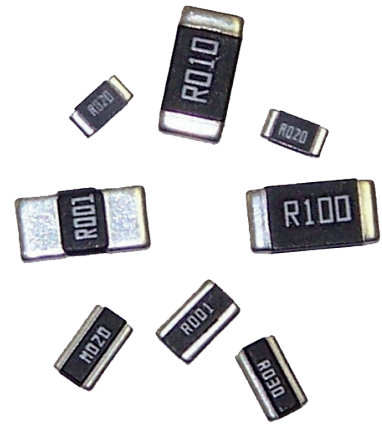


LRMA Series

Features

- Resistance range 0.5mΩ to 500mΩ
- High temperature operation to 170°C
- Low thermal EMF version
- High power version
- Current sensing for power electronics
- RoHS compliant & halogen free
- AEC-Q200 qualified



All parts are Pb-free and comply with EU Directive 2011/65/EU amended by (EU) 2015/863 (RoHS3)

Electrical Data

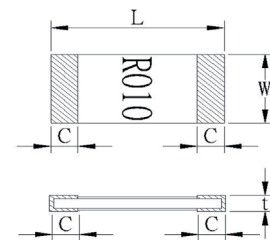
LRMA Version	T (Standard)		P (Power)
Size	2010	2512	2512
Power rating @70°C	W	1.5	≤R10: 3, >R10: 2
Overload rating (5s)	W	7.5	≤R10: 15, >R10: 10
Resistance range	mΩ	2 to 50	0.5 to 500
Standard values ¹	mΩ	2, 5, 6, 10, 15, 20, 50	1, 1.5, 2, 3, 3.5, 4, 5, 6, 7, 8, 10, 11, 12, 15, 18, 20, 25, 30, 33, 35, 40, 50, 100
Resistance tolerance	%	0.5 ¹ , 1, 5	
TCR (25 to 125°C)	ppm/°C	≥R01: ±75	>R001 & <R01: ±100, ≤R001: ±275
Ambient temperature	°C	-55 to 170	
Insulation resistance	MΩ	>100	
Element alloy	Cu-Ni		Cu-Ni / Mn-Cu

LRMA Version	M (Low thermal EMF)			N (Inverse)		
Size	0805	1206	2512	0612	0815	1225
Power rating @70°C	W	0.5	1	≤R01: 2, >R01: 1	1 ²	3
Overload rating (5s)	W	2.5	5	≤R01: 10, >R01: 5	5	15
Resistance range	mΩ	1 to 25	1 to 50	0.5 to 50	1 to 10	1 to 30
Standard values ¹	mΩ	1, 2, 3, 5, 6, 8, 9, 10, 20, 25	1, 1.2, 2, 2.5, 3, 4, 5, 6, 7, 8, 9, 10, 12, 14, 15, 18, 20, 22, 25, 30, 39, 40, 50	0.5, 0.75, 1, 1.5, 2, 3.5, 5, 10, 20, 25, 30, 40, 50	1, 3, 5, 10	1, 2, 3, 4, 5, 10, 15, 20, 25, 30
Resistance tolerance	%	0.5 ¹ , 1, 5			±100	
TCR (25 to 125°C)	ppm/°C	±100	±50	≥R01: ±75, >R001 & <R01: ±100	≤R001: ±275	
Ambient temperature	°C	-55 to 170°C				
Insulation resistance	MΩ	>100				
Element alloy	Mn-Cu			Mn-Cu / Cu-Ni		

Notes: 1. Non-standard values and 0.5% tolerance may be available for high volume requirements. 2. Requires 300mm² copper pad & trace area

Physical Data (All dimensions in mm and nominal weight in mg)

Size	L	W	C	t	Wt
0805	2.0 ±0.1	1.25 ±0.1	0.4 ±0.2	0.6 ±0.2	5.5
0805 ≤R002			0.6 ±0.2		
1206 <R002	3.2 ±0.2	1.6 ±0.2	1.1 ±0.3	0.75 ±0.2	18.3
1206 ≥R002			0.5 ±0.3		
0612	1.7 ±0.2	3.2 ±0.2	0.4 ±0.2	0.6 ±0.2	12.9
0815	2.3 ±0.2	3.75 ±0.3	0.5 ±0.2	0.7 ±0.2	14.1
2010	5.0 ±0.2	2.5 ±0.2	0.6 ±0.3	0.6 ±0.2	35.6
2512 <R001	6.4 ±0.2	3.2 ±0.2	2.6 ±0.2	0.6 ±0.2	57 to 63
2512 ≥R001 & ≤R003 ¹			2.2 ±0.2		
2512 >R003 ¹			0.9 ±0.2		
1225	3.2 ±0.3	6.4 ±0.3	0.5 ±0.2	0.9 ±0.2	70



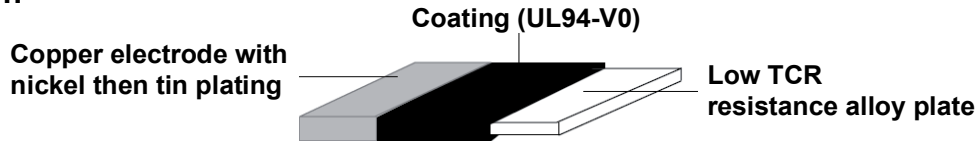
Note 1 - This applies to LRMAT2512 and LRMAM2512. For LRMAP2512 this threshold is R004

General Note

TT Electronics reserves the right to make changes in product specification without notice or liability. All information is subject to TT Electronics' own data and is considered accurate at time of going to print.

LRMA Series

Construction



Marking

The components are marked with ohmic value, e.g. "R002" = 2mΩ, "R010" = 10 mΩ. Due to space restrictions, for LRMAM1206-R001, "01" = 1mΩ is used, and for LRMAM0805, "2" = 2mΩ, "010" = 10 mΩ are used.

Solvent Resistance

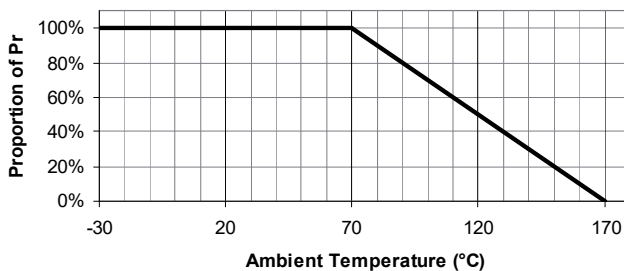
The component is resistant to all normal industrial cleaning solvents suitable for printed circuits.

Performance Data

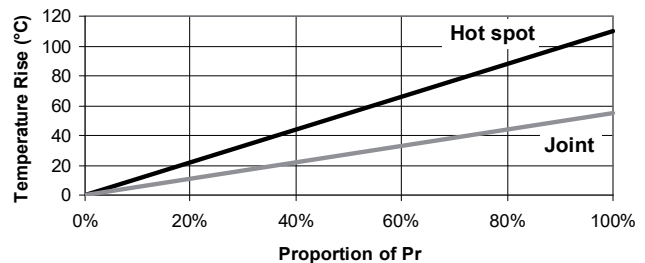
		Maximum (%)	Typical (%)
Load at rated power (cyclic load, 1000 hours at 70°C)	±ΔR	0805: 1.5 Others 1	0.3
Short term overload (5 x rated power for 5s)	±ΔR	0.5	0.15
Humidity (1000 hours, 85°C, 85%RH)	±ΔR	0805: 1 Others 0.5	0.15
Temperature cycle (-40 to +125°C, 1000 cycles, 15 minute dwell)	±ΔR	0805: 1 Others 0.5	0.15
Resistance to solder heat (260°C ±5°C for 20s ±1s)	±ΔR	0.5	0.3
Solderability (245°C ±5°C for 2s ±0.5s)		>95% coverage	
Dry heat (1000 hours at 170°C)	±ΔR	0805: 1.5 Others 0.5	0.3
Low temperature storage (1000 hours at -55°C)	±ΔR	0.5	0.15
Substrate bending (board 1.6mm, fulcrum spacing 90mm, deflection 2mm)	±ΔR	0805: 1 Others 0.5	0.3
Insulation resistance (1 minute @ 100Vdc)		>100M	
Sulphur Resistance (ASTM B-809-95 (modified) 105°C dry, 1000 hours. Visual inspection x10)		Pass	

Thermal Performance & Mounting

Temperature Derating

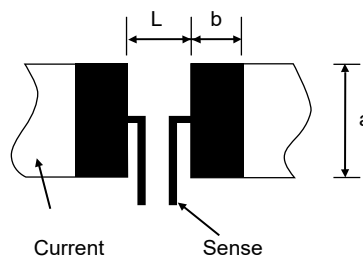


Typical Temperature Rise



Reference Pad Dimensions (mm)

Size	a	b	L
0612	3.8	0.7	0.7
0805	1.4	1.15	1.2
1206 <R002	1.8	2.3	1.0
1206 ≥R002	1.8	1.7	1.6
0815 >R01	7.9	1.5	0.9
0815 ≤R01	4.2	0.8	1.2
2010	3.4	1.5	3.5
2512 ≤R003 ¹	4.0	3.1	1.3
2512 >R003 ¹	4.0	2.1	4.1
1225	7.0	1.0	2.3



The temperature rise shown is highly dependent on mounting conditions. Reference conditions assume 20μ copper with thermal vias to multiple layers. The self-heating in the current tracks should be kept negligible, or allowed for by temperature derating.

Note 1 - This applies to LRMAT2512 and LRMAM2512. For LRMAM2512 this threshold is R004

Standard 4-terminal probe pitches for measuring unmounted parts are 2.8 x 1.7mm (0612), 0.4 x 1.83mm (0805), 0.4 x 2.8mm (1206), 1.2 x 4.5mm (2010), 1.5 x 5.8mm (2512), and 5.4 x 3.4mm (1225). All probe location tolerances ±0.02mm. These resistors are designed to have the correct ohmic value when mounted on a PCB. Probed measurements may read higher values and mounting offsets may need to be established to account for this, especially with sub-milliohm values.

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LRMA Series

Packaging

Size	Tape	A	B	W	F	E	P ₁	P ₂	P ₀	φD ₀	t	φA	φB	φC	Wr	Tr
0805	Paper	1.6 ±0.15	2.4 ±0.2	8.0 ±0.2	3.5 ±0.05	1.75 ±0.1	4.0 ±0.1	2.0 ±0.1	4.0 ±0.1	1.5 +0.1/-0	0.84 ±0.1	178 ±2	60 ±1	13 ±1	9 ±1	11.4 ±1
0612, 1206	Paper	2.0 ±0.15	3.6 ±0.2	8.0 ±0.2	3.5 ±0.05	1.75 ±0.1	4.0 ±0.1	2.0 ±0.05	4.0 ±0.1	1.5 +0.1/-0	0.84 ±0.1	178 ±2	60 ±1	13 ±1	9 ±1	11.5 ±1
0815	Emboss	2.6 ±0.2	4.5 ±0.2	12 ±0.2	5.5 ±0.1	1.75 ±0.1	4.0 ±0.1	2.0 ±0.2	4.0 ±0.1	1.55 ±0.05	1.1 ±0.1	178 ±2	60 ±1	13 ±1	13 ±1	15.4 ±2
2010	Emboss	2.8 ±0.2	5.3 ±0.2	12 ±0.05	5.5 ±0.05	1.75 ±0.1	4.0 ±0.1	2.0 ±0.05	4.0 ±0.05	1.5 +0.1/-0	0.85 ±0.15	178 ±2	60 ±1	13 ±1	13 ±1	15.4 ±2
2512 1225	Emboss	3.6 ±0.2	6.9 ±0.2	12 ±0.2	5.5 ±0.05	1.75 ±0.1	4.0 ±0.1	2.0 ±0.05	4.0 ±0.05	1.5 +0.1/-0	0.85 ±0.15	178 ±2	60 ±1	13 ±1	13 ±1	15.4 ±2

Storage

Conditions: 5°C to 35°C and 40% to 75%RH

Shelf life: 2 years from manufacture

Processing

LRMA series resistors are suitable for both wave and IR reflow soldering. The recommended reflow profile for Pb-free SAC305 alloy (Sn 96.5%, Ag 3%, Cu 0.5%) soldering is as follows:

Pre-heat: 60s to 120s at 150°C to 180°C

Soldering: 20s to 40s at ≥230°C

Peak: 5s at 255°C to 260°C

Ordering Procedure

Example: LRMAM2512-R01FT4 (LRMA2512, low thermal EMF, 10 milliohms ±1%, Pb-free)



1	2	3	4	5	6		
Type	Version	Size	Value	Tolerance	Packing		
LRMA	T	Standard	3 to 6 characters	D = ±0.5%	Tape & reel		
	P	Power		F = ±1%	T5	0612, 0805, 1206	5000/reel
	M	Low thermal EMF	R = ohms	J = ±5%	T4	0815, 2010, 2512, 1225	4000/reel
	N	Inverse	0815				
		2010					
		2512					
		1225					

Note 1: For values which require all 6 characters, e.g. R00075, the hyphen is omitted.

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